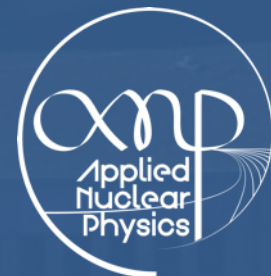


# Development and Deployment of Advanced Detector Systems from the Semiconductor Detector Laboratory

**Paul Barton**

Applied Nuclear Physics Program

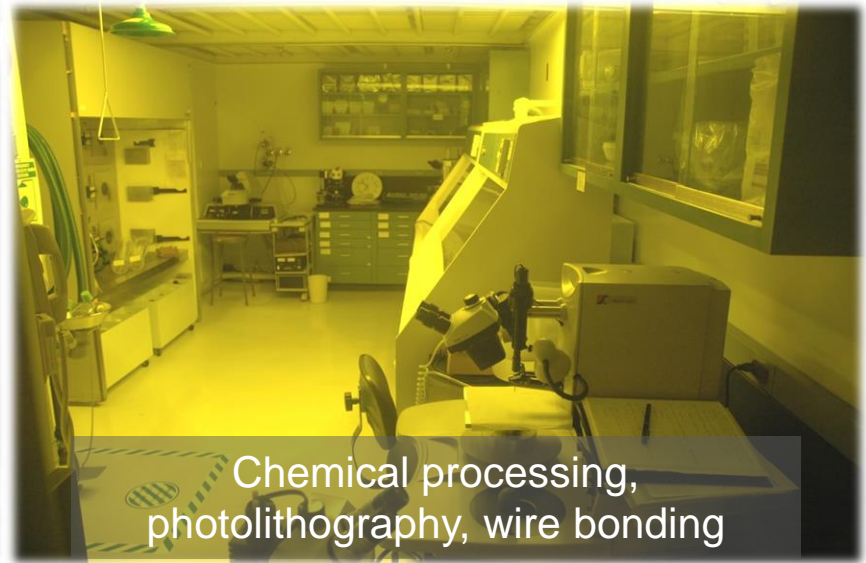
Nuclear Science Division, Director's Review  
October 26<sup>th</sup> 2016



# LBNL Semiconductor Detector Laboratory (SDL)



Thin-film deposition



Chemical processing,  
photolithography, wire bonding



Detector characterization

Infrastructure and expertise  
for the development and  
production of semiconductor-  
based radiation detectors  
and detection systems

# Detector Group at LBNL



## Historical accomplishments with significant impact to radiation detector technology:

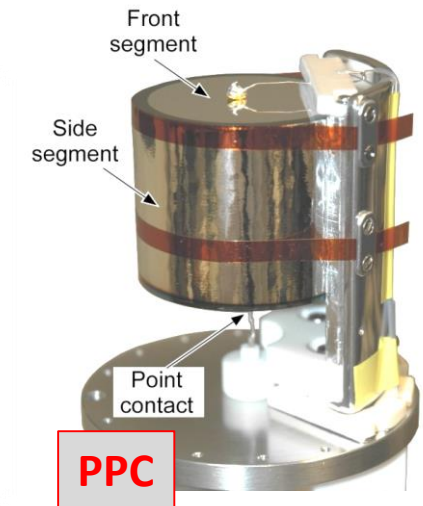
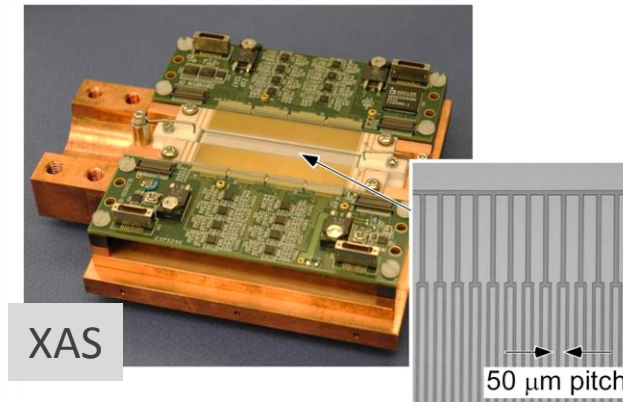
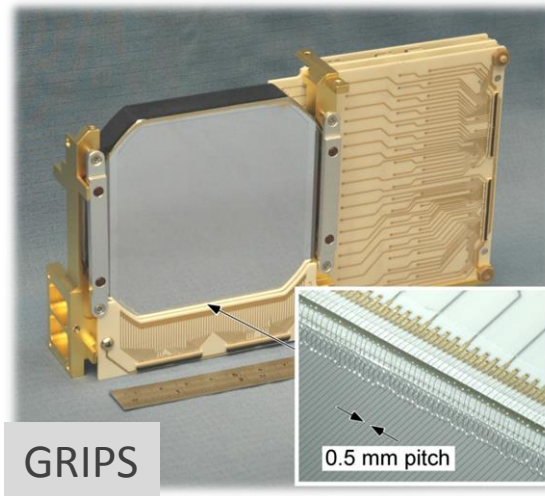
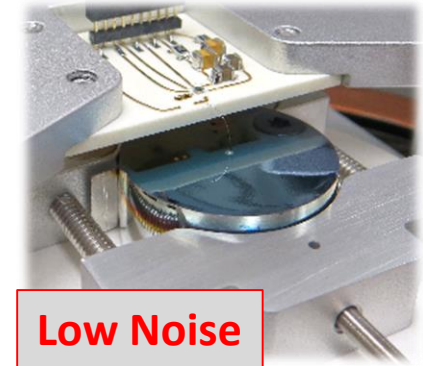
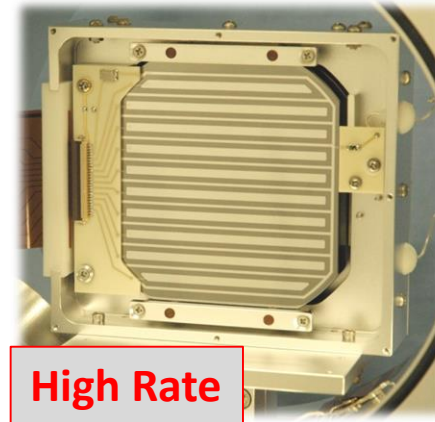
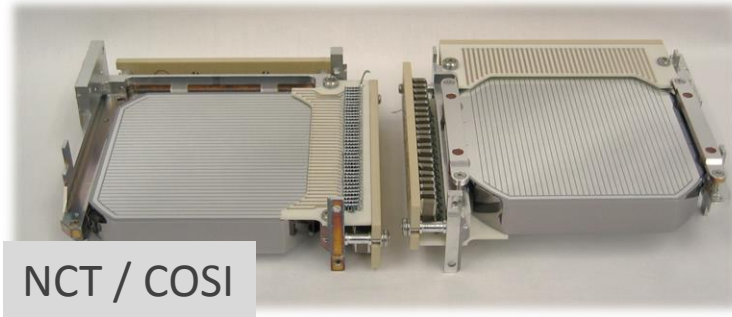
- One of first groups to develop lithium-drifted **Si:Li** detectors (early 1960's)
- One of two groups that originally developed high-purity Ge (**HPGe**) crystal growth (early 1970's)
- First Si and Ge **drift detectors** produced in our laboratories
- Fabrication technologies developed include: **amorphous semiconductor** contact, implanted contact, and surface passivation
- Developed position-sensitive Si and Ge **strip detectors**
- Invented shaped-field **point-contact Ge** detector (1989)
- Invented **coplanar-grid** technique for CdZnTe-based detectors (1994)
- Invented **proximity charge-sensing** readout technique (2009)
- Developed **low-noise** electronics for semiconductor detectors



# LBNL Semiconductor Detector Laboratory (SDL) Ge Detector Technologies



Advanced detectors from HPGe crystals: segmented, high rate, low noise



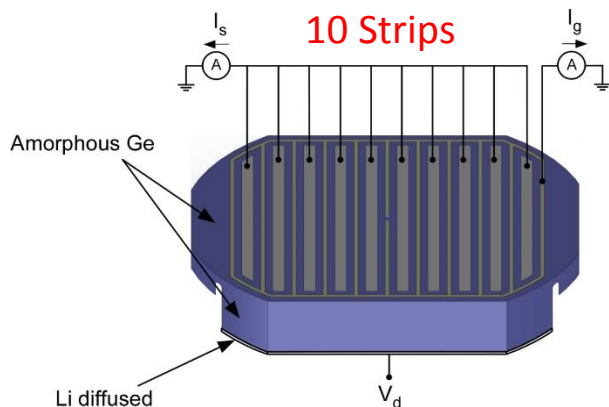
Advanced detectors require similar investment in readout integration.

# High Rate Germanium

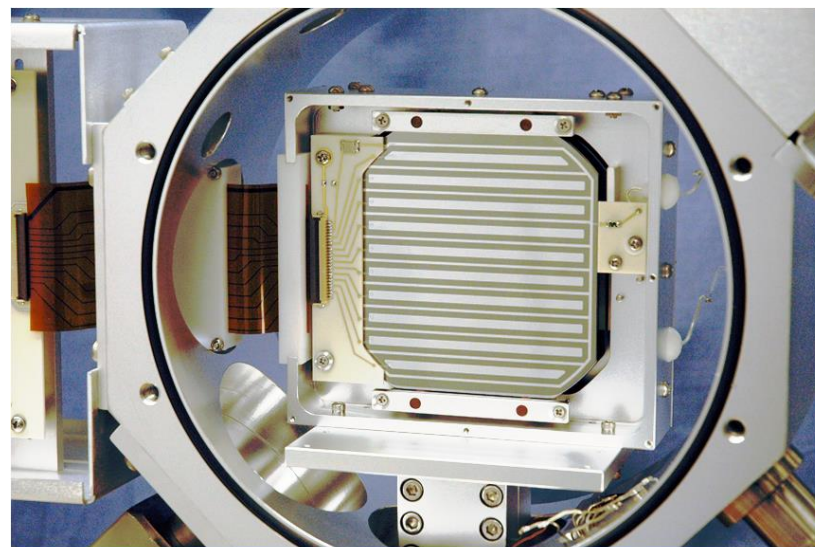
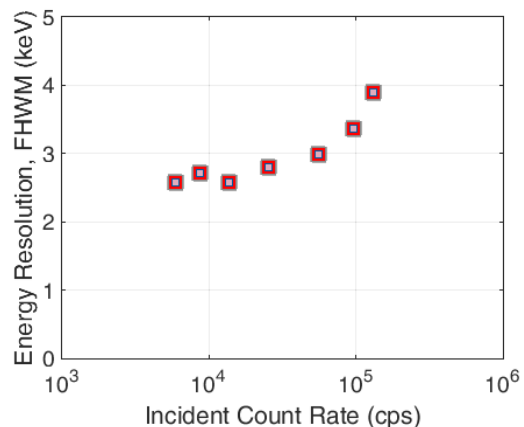
\*funded by DOE NNSA

## Primary Application:

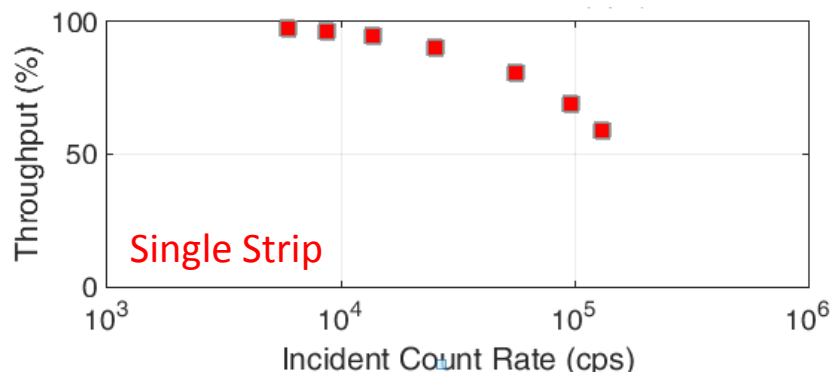
Spent nuclear fuel assay,  
maintaining energy resolution at high rates



Optimized steering grid and strip capacitances.



Test cryostat for segmented high-rate Ge detector.

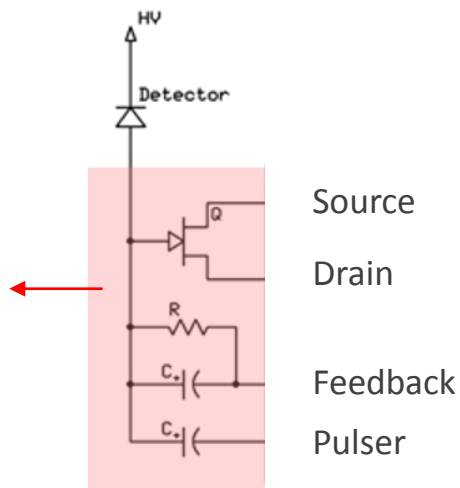
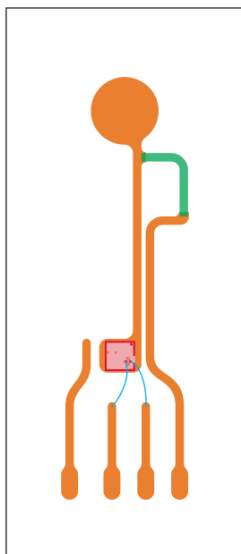


**Towards:** mechanically-cooled, ASIC-readout, signal decomposition.

# Low Mass Front End (LMFE) Readout Electronics for Point Contact HPGe

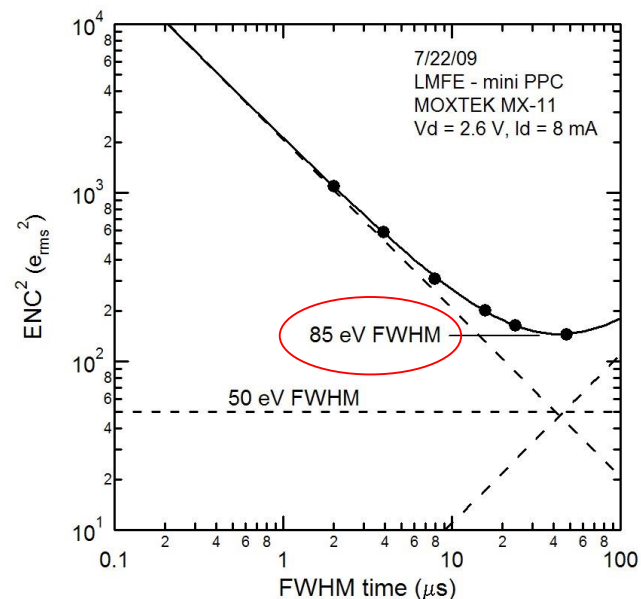
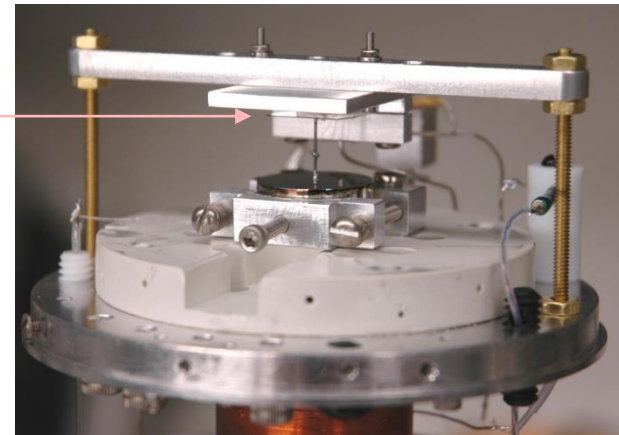
## Key Features:

- Fused silica substrate
- Bare die low-capacitance JFET
- Amorphous Ge feedback resistor
- Au trace proximity capacitors



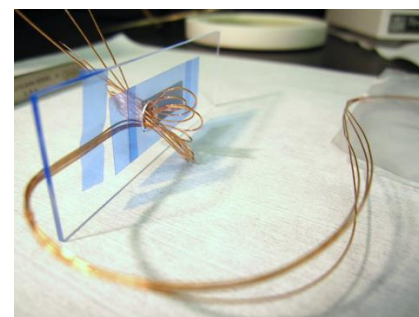
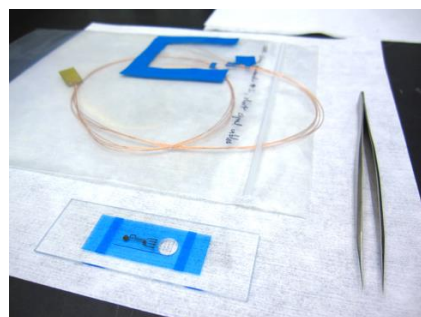
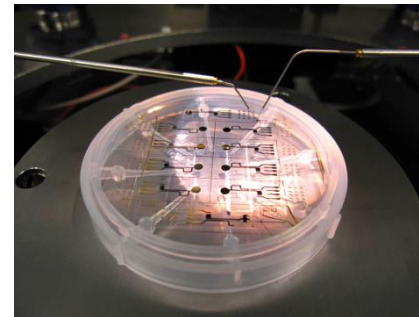
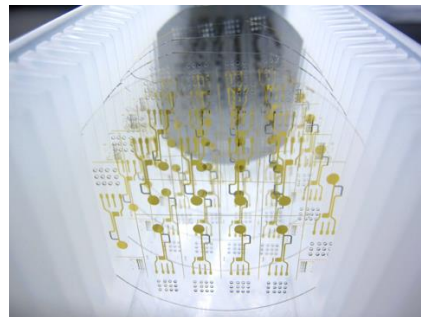
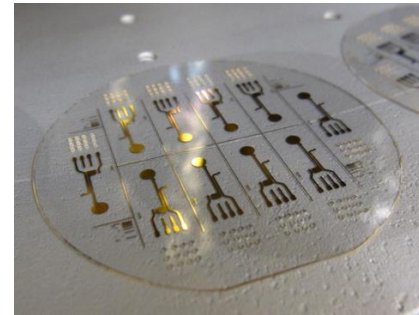
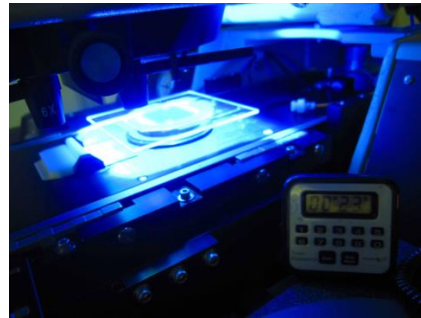
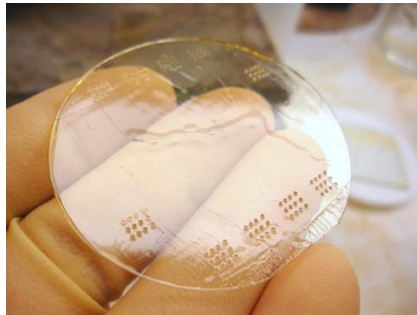
LMFE design for the MAJORANA Demonstrator

LMFE



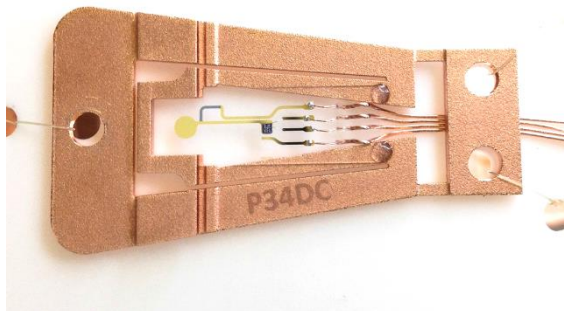


# LMFE Fabrication at the SDL

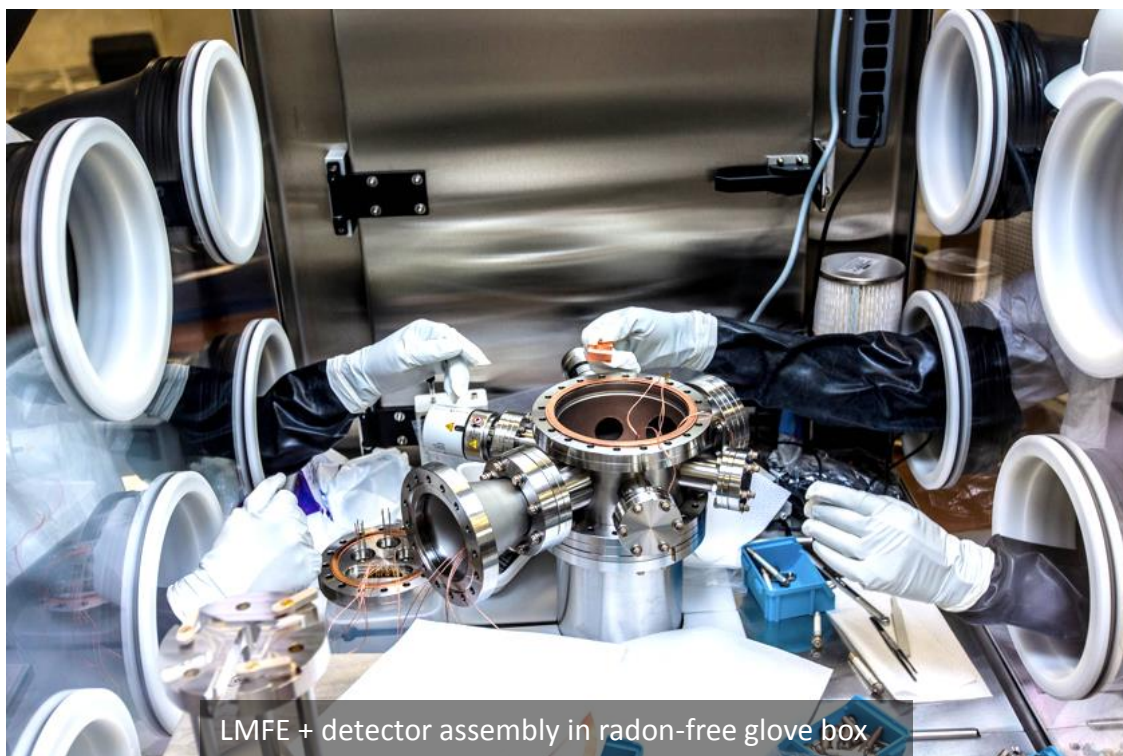


Low background thin film processing, testing and assembly of **150+ modules**

# MAJORANA Demonstrator Assembly



LMFE modules are carefully installed with a low-background pin to each detector's point contact, achieving **165 eV-FWHM** electronic noise.



LMFE + detector assembly in radon-free glove box



Sanford Underground Research Facility

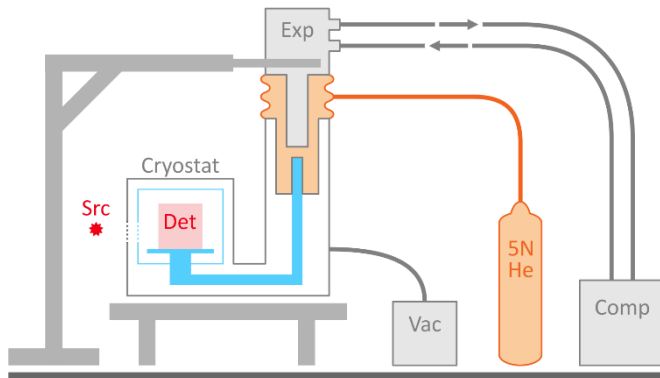


# Ultra-Low Noise HPGe for Coherent Neutrino Nucleus Scattering



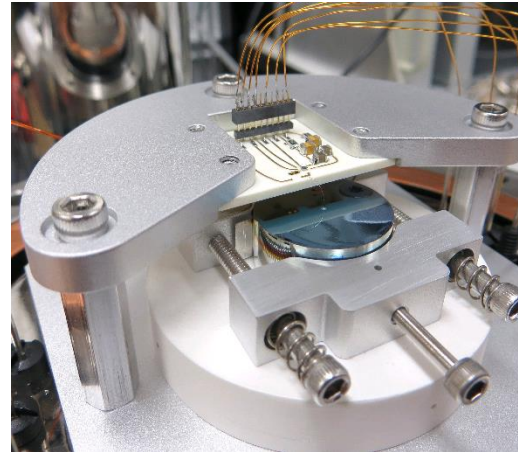
\*Funded by DOE NNSA

**The First:** Mechanically Cooled, Wirebonded PPC HPGe, with CMOS Front End



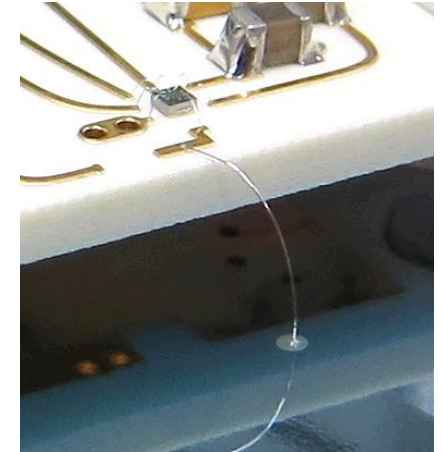
## Atmospheric Pressure He Gas

Provides **ultra-low vibration** thermal link  
using standard GM cycle (**10 – 80 K**)  
→ Eliminates all vibrations



## Ultra-Low Capacitance

Smaller point contact (**0.26 pF**)  
enabled by wire bonding  
→ Ultra-Low Electronic Noise



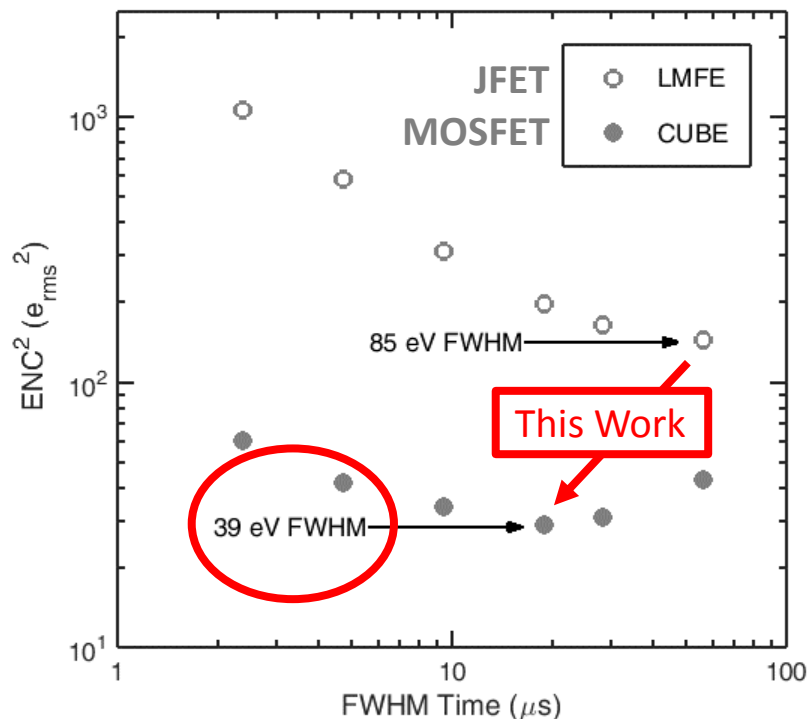
## Preamplifier-on-a-Chip

**CMOS** ASIC for SDD  
4 electrons-rms noise  
→ Better than JFET  
at low temperatures

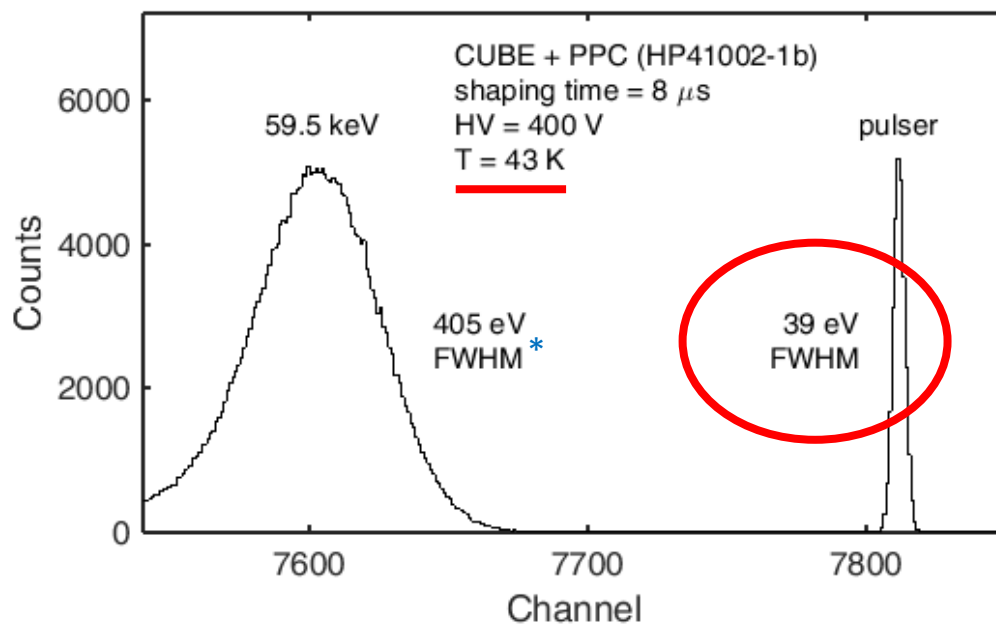
**Low temperature** and **low capacitance** of CMOS and Ge.  
**Result:** lowest noise HPGe detector: **39 eV-FWHM** at 40 K.

# Ultra Low Noise Results from ULGeN Project

## Equivalent Noise Charge



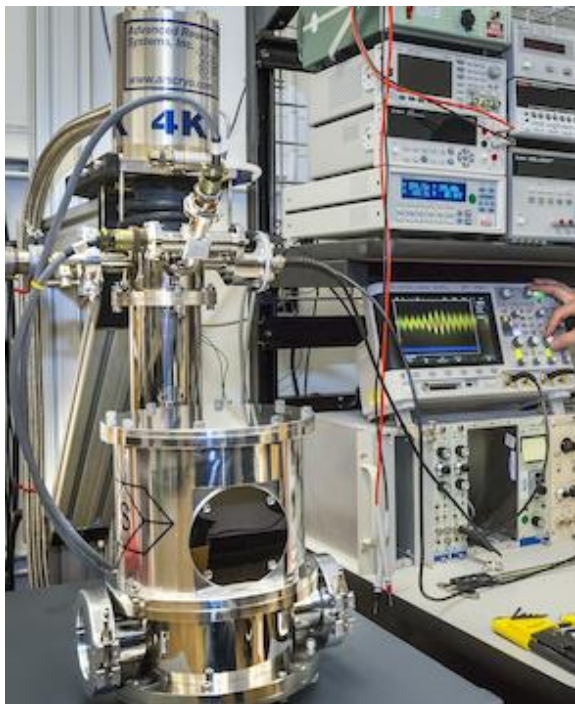
## $^{241}\text{Am}$ Spectrum with Pulser



\* 356 eV-FWHM (Fano limit) at 90 K

All noise components improved by combination of  
**low temperature and low capacitance**

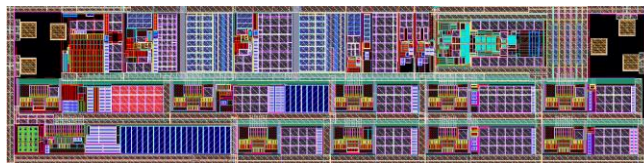
# Lower Noise Electronics for Coherent Neutrino Scattering



## Ge Quenching Factor Measurement at TAMU (2016)

Ultra-Low Noise HPGe detector system moved to TAMU reactor and neutron beam to measure lowest energy nuclear recoil quenching factor.

LNC (Low Noise / Capacitance) ASIC  
designed at BNL



## ASIC Features:

1. Lower threshold  
(target <3 e-rms noise)
2. Low input capacitance  
(targeting 0.1 pF detectors)
3. Fewer connections (Pwr,Gnd,In,Out)  
(minimizes cabling + backgrounds)
4. On-board filters  
(reduces external components + backgrounds)

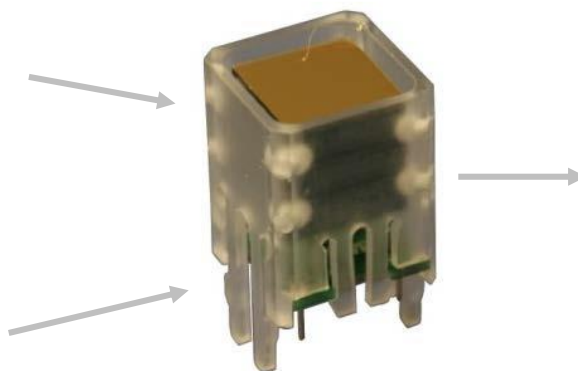
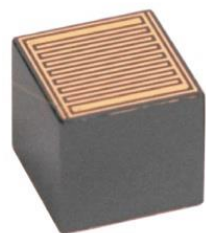
**Also supporting: low-energy program for ton-scale HPGe.**



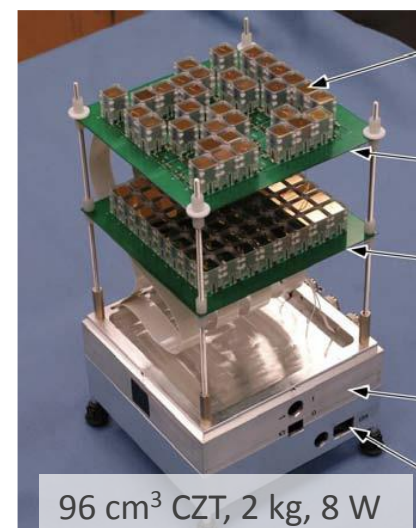
# High Efficiency Multimode Imager (HEMI)

\*funded by DHS DNDO

1.5 – 2.5% FWHM at 662 keV



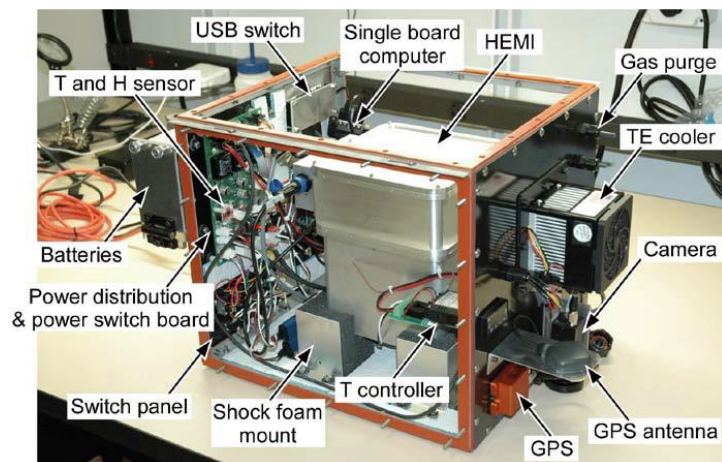
**Coded  
Aperture  
+  
Compton  
Imaging**  
(30-3000 MeV)



CPG detector elements  
Partially populated coded mask front detector plane  
Fully populated back detector plane  
DAQ signal readout boards  
High voltage and power supply board

96 cm<sup>3</sup> CZT, 2 kg, 8 W

Active-Mask HEMI Instrument



Ruggedized HEMI flight module



HEMI on RMAX helicopter flight in Fukushima

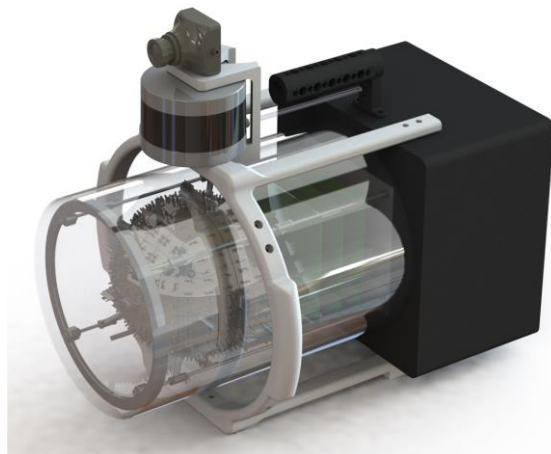
# PRISM – A CdZnTe-Based Portable Radiation Imaging, Spectroscopy and Mapping System



\*funded by DOD DTRA



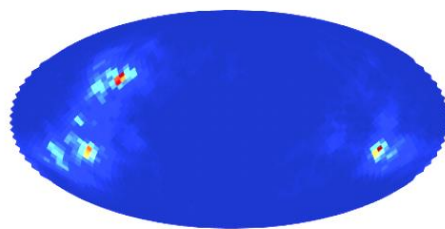
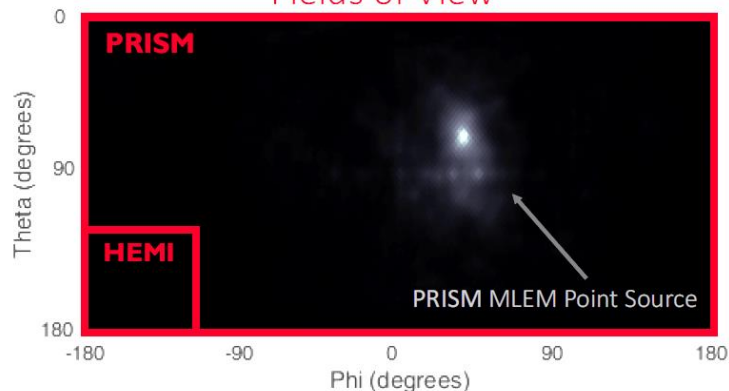
**HEMI** with contextual sensors  
(LIDAR, Camera)



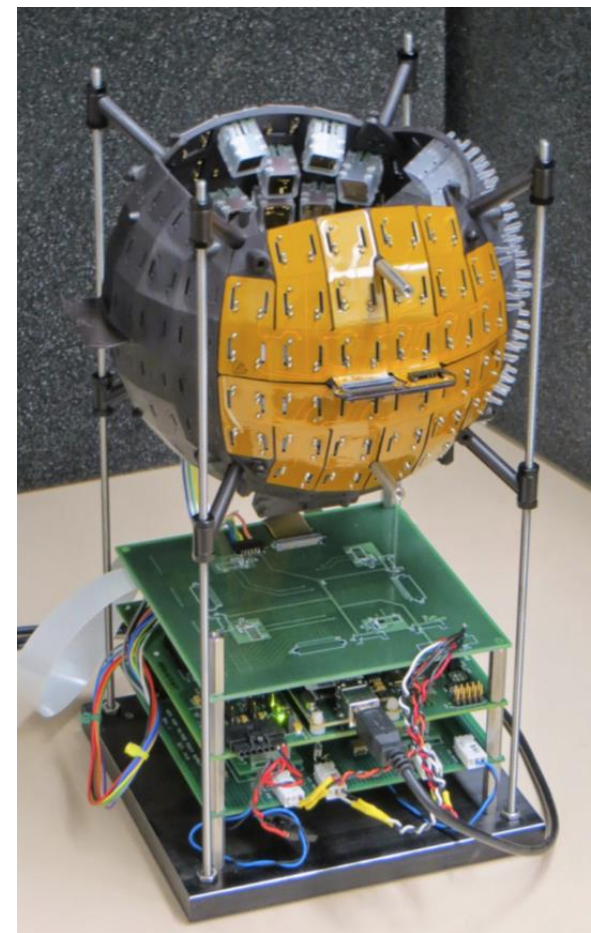
**PRISM** Prototype Concept  
with spherical detector arrangement

## First Spherical Coded Aperture Imager (simulations)

Fields of View



4 $\pi$  imaging of multiple  
60 keV point sources



**PRISM** Bench Prototype

# Advances and Opportunities for the NSD-Supported SDL



## Advances

- Highly integrated HPGe strip detectors (**0.5 mm pitch**)
- High count rate HPGe strip detectors (**> 1 Mcps**)
- Lowest noise HPGe point contact detector (**34 eV-FWHM**)
- Fielded broad-energy CZT Imager (**Fukushima & more**)
- First “coded sphere” CZT Imager ( **$4\pi$  coded aperture + Compton**)

## Opportunities

- **Mechanical cooling** integration for portable / reliable HPGe
- **CMOS integration** for strip and point contact HPGe detectors
- **CMOS integration** for portable CZT imagers